

Fast Recovery Epitaxial Diode (FRED) Module

MEA 95-06 DA
MEK 95-06 DA
MEE 95-06 DA

$V_{RRM} = 600 \text{ V}$
 $I_{FAV} = 95 \text{ A}$
 $t_{rr} = 250 \text{ ns}$

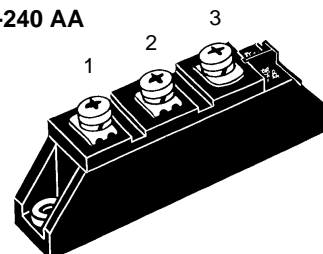
| V_{RSM} V | V_{RRM} V | Type |
|----------------|----------------|--------------|
| 600 | 600 | MEA95-06 DA |
| | | MEK 95-06 DA |
| | | MEE 95-06 DA |

| Symbol | Test Conditions | Maximum Ratings | |
|---------------|--|-----------------|----------------------|
| I_{FRMS} | $T_{case} = 75^{\circ}\text{C}$ | 142 | A |
| $I_{FAV}^{①}$ | $T_{case} = 75^{\circ}\text{C}$; rectangular, $d = 0.5$ | 95 | A |
| I_{FRM} | $t_p < 10 \mu\text{s}$; rep. rating, pulse width limited by T_{VJM} | TBD | A |
| I_{FSM} | $T_{VJ} = 45^{\circ}\text{C}$; $t = 10 \text{ ms}$ (50 Hz), sine | 1200 | A |
| | $t = 8.3 \text{ ms}$ (60 Hz), sine | 1300 | A |
| | $T_{VJ} = 150^{\circ}\text{C}$; $t = 10 \text{ ms}$ (50 Hz), sine | 1080 | A |
| | $t = 8.3 \text{ ms}$ (60 Hz), sine | 1170 | A |
| I^2t | $T_{VJ} = 45^{\circ}\text{C}$; $t = 10 \text{ ms}$ (50 Hz), sine | 7200 | A^2s |
| | $t = 8.3 \text{ ms}$ (60 Hz), sine | 7100 | A^2s |
| | $T_{VJ} = 150^{\circ}\text{C}$; $t = 10 \text{ ms}$ (50 Hz), sine | 5800 | A^2s |
| | $t = 8.3 \text{ ms}$ (60 Hz), sine | 5700 | A^2s |
| T_{VJ} | | -40...+150 | $^{\circ}\text{C}$ |
| T_{stg} | | -40...+125 | $^{\circ}\text{C}$ |
| T_{Hmax} | | 110 | $^{\circ}\text{C}$ |
| P_{tot} | $T_{case} = 25^{\circ}\text{C}$ | 280 | W |
| V_{ISOL} | 50/60 Hz, RMS $t = 1 \text{ min}$ | 3000 | V~ |
| | $I_{ISOL} \leq 1 \text{ mA}$ $t = 1 \text{ s}$ | 3600 | V~ |
| M_d | Mounting torque (M5) | 2.5-4/22-35 | Nm/lb.in. |
| | Terminal connection torque (M5) | 2.5-4/22-35 | Nm/lb.in. |
| d_s | Creep distance on surface | 12.7 | mm |
| d_A | Strike distance through air | 9.6 | mm |
| a | Maximum allowable acceleration | 50 | m/s^2 |
| Weight | | 90 | g |

| Symbol | Test Conditions | Characteristic Values (per diode) | |
|------------|---|-----------------------------------|-----------------------|
| | | typ. | max. |
| I_R | $T_{VJ} = 25^{\circ}\text{C}$ $V_R = V_{RRM}$ | | 2 mA |
| | $T_{VJ} = 25^{\circ}\text{C}$ $V_R = 0.8 \cdot V_{RRM}$ | | 0.5 mA |
| | $T_{VJ} = 125^{\circ}\text{C}$ $V_R = 0.8 \cdot V_{RRM}$ | | 34 mA |
| V_F | $I_F = 100 \text{ A}$; $T_{VJ} = 125^{\circ}\text{C}$ | | 1.36 V |
| | $T_{VJ} = 25^{\circ}\text{C}$ | | 1.55 V |
| | $I_F = 300 \text{ A}$; $T_{VJ} = 125^{\circ}\text{C}$ | | 2.05 V |
| | $T_{VJ} = 25^{\circ}\text{C}$ | | 2.09 V |
| V_{T0} | For power-loss calculations only | | 1.01 V |
| r_T | $T_{VJ} = 125^{\circ}\text{C}$ | | 2.85 $\text{m}\Omega$ |
| R_{thJH} | DC current | | 0.550 K/W |
| R_{thJC} | DC current | | 0.450 K/W |
| t_{rr} | $I_F = 100 \text{ A}$ $T_{VJ} = 100^{\circ}\text{C}$ | 250 | 300 ns |
| I_{RM} | $V_R = 300 \text{ V}$ $T_{VJ} = 25^{\circ}\text{C}$ | | 14 A |
| | $-di/dt = 200 \text{ A}/\mu\text{s}$ $T_{VJ} = 100^{\circ}\text{C}$ | | 21 A |

① I_{FAV} rating includes reverse blocking losses at T_{VJM} , $V_R = 0.6 V_{RRM}$, duty cycle $d = 0.5$
Data according to IEC 60747
IXYS reserves the right to change limits, test conditions and dimensions

TO-240 AA



Features

- International standard package with DCB ceramic base plate
- Planar passivated chips
- Short recovery time
- Low switching losses
- Soft recovery behaviour
- Isolation voltage 3600 V~
- UL registered E 72873

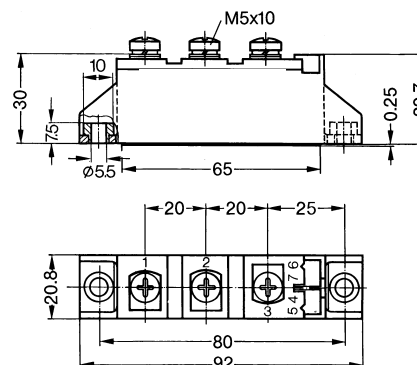
Applications

- Antiparallel diode for high frequency switching devices
- Free wheeling diode in converters and motor control circuits
- Inductive heating and melting
- Uninterruptible power supplies (UPS)
- Ultrasonic cleaners and welders

Advantages

- High reliability circuit operation
- Low voltage peaks for reduced protection circuits
- Low noise switching
- Low losses

Dimensions in mm (1 mm = 0.0394")



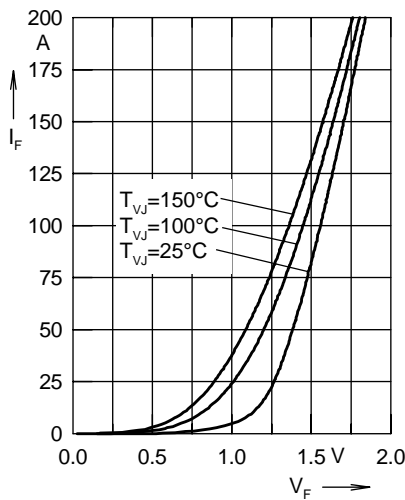


Fig. 1 Forward current I_F versus voltage drop V_F per leg

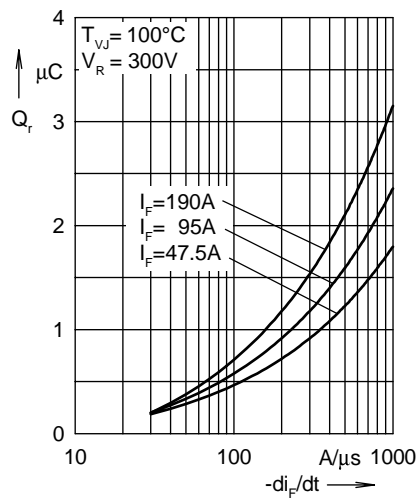


Fig. 2 Reverse recovery charge Q_r versus $-di_F/dt$

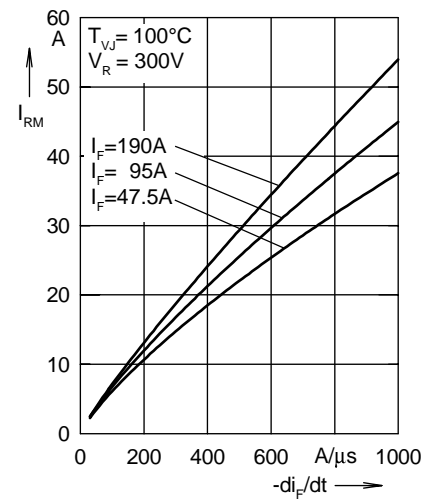


Fig. 3 Peak reverse current I_{RM} versus $-di_F/dt$

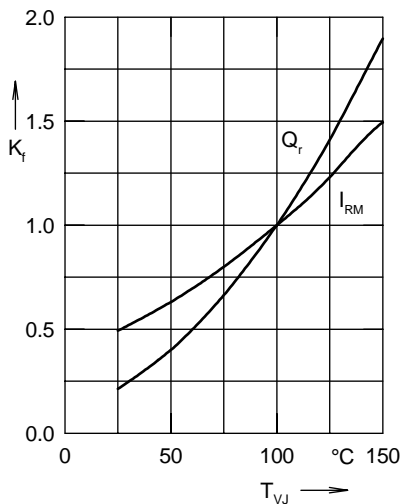


Fig. 4 Dynamic parameters Q_r , I_{RM} versus junction temperature T_{VJ}

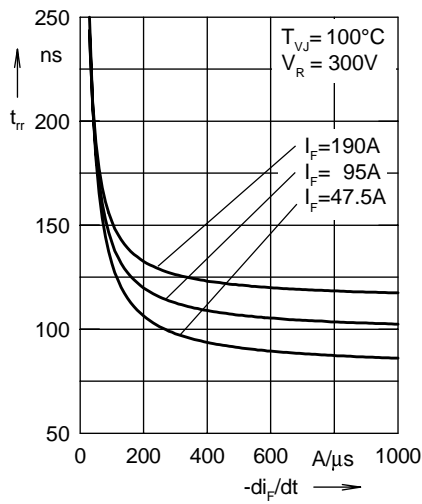


Fig. 5 Recovery time t_{rr} versus $-di_F/dt$

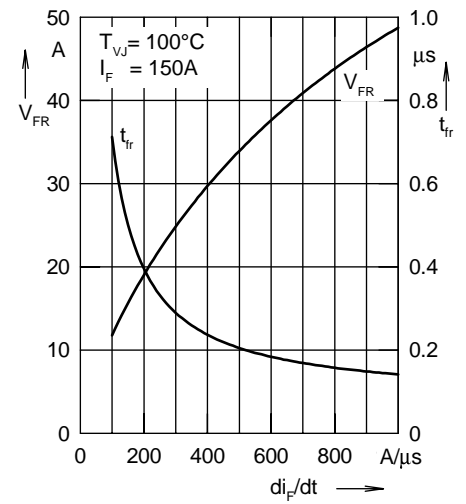


Fig. 6 Peak forward voltage V_{FR} and t_{rr} versus di_F/dt

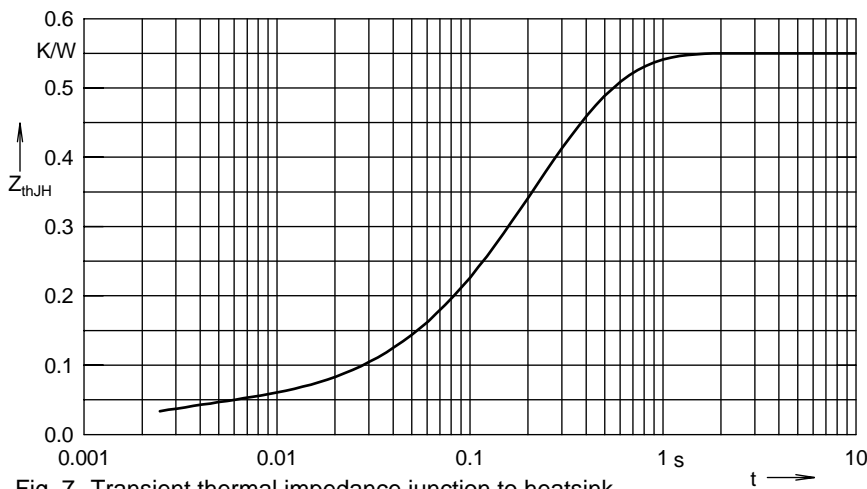


Fig. 7 Transient thermal impedance junction to heatsink

Constants for Z_{thJH} calculation:

| i | R_{thi} (K/W) | t_i (s) |
|---|-----------------|-----------|
| 1 | 0.037 | 0.002 |
| 2 | 0.138 | 0.134 |
| 3 | 0.093 | 0.25 |
| 4 | 0.282 | 0.274 |